



Capabilities | Rigid

Layer Count	<ul style="list-style-type: none">• 1 - 58 layer
Finished Board Thickness	<ul style="list-style-type: none">• 0.4 - 3.2 mm (> 3.2 mm on request)
Max. Production Panel Size	<ul style="list-style-type: none">• 520 mm x 620 mm
Min. Line Width/ Line Space	<ul style="list-style-type: none">• 0.075mm
Min. Hole Size (Finished) <ul style="list-style-type: none">• Mechanical• Laser	<ul style="list-style-type: none">• 0.2 mm• 0.1 mm
Laminate Main Brands: Shengyi, Kjnboard, Ventec, ITEQ, Doosan	<ul style="list-style-type: none">• CEM-1• CEM-3<ul style="list-style-type: none">• CTI ≥600• FR-4<ul style="list-style-type: none">• Maximum Tg 170• Anti CAF• Halogen free• BT epoxy• PTFE Ceramic• High frequency materials• Aluminum substrate• Copper substrate
Solder Mask Color Main brands: Tamura, Taiyo, OTC, Huntsman	<ul style="list-style-type: none">• Green (glossy semi-matte matte)• Blue• Black• White• Red
Surface Finish	<ul style="list-style-type: none">• HAL (leadfree)• Immersion Nickel Gold• Galvanic Nickel Gold• Immersion Tin• Immersion Silver• OSP• Peelable solder mask• Gold Finger• Carbon Ink Print
Profiling	<ul style="list-style-type: none">• Routing Depth Routing• Punching• V-scoring Jump V-scoring
Additional Technology	<ul style="list-style-type: none">• HDI boards (micro via, blind via, buried via)• Resin plugging of via holes, copper plugging of micro via• Silver Through Hole• Press-fit hole
Lead Time	<ul style="list-style-type: none">• Express service: 15 days (FCA HK)• Mass Production: 4 - 6 weeks (FCA HK)



Capabilities | Flex and Rigid-Flex

Lot Size	• Prototypes up to Mass Production	
Layer Count	• Rigid-Flex: 2 – 10 Layer • Flex: 1 – 8 Layer	
Finished Board Thickness	• Rigid-Flex: 0.2 – 3.2 mm • Flex: 0.15 – 1.0 mm	
Max. Production Panel Size	• 250mm x 1000mm (2L) • 250mm x 500 mm (ML)	
Laminate Main Brands: Aplus , Innox (Flex), Shengyi (Rigid)	Rigid • FR-4	Flex • CCL (PI and PET) • Coverlay (PI and PET) • Copper (RA and ED)
Solder Mask Color Main Brands: Taiyo	• Green • Yellow • Amber	• Blue • Black • White
Surface Finish	• HAL • HAL LF • Immersion Nickel Gold	• Galvanic Nickel Gold • Immersion Tin • OSP • Immersion Silver
Profiling	• Punching (Mass Production) • Laser Cutting (Sample Production) • Routing (Sample Production)	
Lead Time	• Express service: 4 days (FCA HK) • Mass Production: 4 - 5 weeks (FCA HK)	
Stiffener	• PSA (pressure sensitive adhesive) • TSA (thermal sensitive adhesive) • Materials: FR-4, Aluminum, PI, PET, 3M Tape	



Capabilities | s.m.a.r.t.

Layer Count	<ul style="list-style-type: none">• 1 – 8 Layers
Max Production Panel	<ul style="list-style-type: none">• 457mm x 610mm
Laminate	<ul style="list-style-type: none">• CEM-1• CEM-3• FR-4 <ul style="list-style-type: none">– Maximum Tg 170– Anti CAF– Halogen Free– CTI \geq600
Finished Board Thickness	<ul style="list-style-type: none">• 0.4mm – 3.2mm
Base Copper Thickness	<ul style="list-style-type: none">• 18 – 105μm
Min. Finished Hole Size	<ul style="list-style-type: none">• 0.2mm (mechanical drilling)
Min. Line Width / Spacing	<ul style="list-style-type: none">• 0.1 / 0.1 mm (sample only)• 0.15 / 0.15 (normal)
Profiling	<ul style="list-style-type: none">• Routing Depth Routing• V-scoring Jump V-scoring
LPI Solder Mask Color	<ul style="list-style-type: none">• Green (glossy semi-matte matte)• Blue <ul style="list-style-type: none">• Black• White• Red
Surface Finish	<ul style="list-style-type: none">• HAL (lead-free)• Immersion Nickel Gold• Galvanic Nickel Gold• Immersion Tin <ul style="list-style-type: none">• Immersion Silver• OSP• Carbon print• Peelable mask
Special Technology	<ul style="list-style-type: none">• Resin Plug
Lead Time	<ul style="list-style-type: none">• Express service: 3-7 days (FCA HK)• Mass Production: 10-20 days (FCA HK)